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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-II
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79rc32v332-133dh

- ◆ **Serial Peripheral Interface (SPI) master mode interface**
- ◆ **UART Interface**
 - 16550 compatible UART
 - Baud rate support up to 1.5 Mb/s
- ◆ **Memory & Peripheral Controller**
 - 6 banks, up to 8MB per bank
 - Supports 8-, 16-, and 32-bit interfaces
 - Supports Flash ROM, SRAM, dual-port memory, and peripheral devices
 - Supports external wait-state generation
 - 8-bit boot PROM support
 - Flexible I/O timing protocols
- ◆ **4 DMA Channels**
 - 4 general purpose DMA, each with endianness swappers and byte lane data alignment
 - Supports scatter/gather, chaining via linked lists of records
 - Supports memory-to-memory, memory-to-I/O, memory-to-PCI, PCI-to-PCI, and I/O-to-I/O transfers
 - Supports unaligned transfers
 - Supports burst transfers
 - Programmable DMA bus transactions burst size (up to 16 bytes)
- ◆ **PCI Bus Interface**
 - 32-bit PCI, up to 50 MHz
 - Revision 2.2 compatible
 - Target or master
 - Host or satellite
 - Two slot PCI arbiter
 - Serial EEPROM support, for loading configuration registers
- ◆ **Off-the-shelf development tools**
- ◆ **JTAG Interface (IEEE Std. 1149.1 compatible)**
- ◆ **208 QFP Package**

- ◆ **3.3V or 2.5V core supply with 3.3V I/O supply**
 - 3.3V core supply is 5V I/O tolerant
- ◆ **EJTAG in-circuit emulator interface**

CPU Execution Core

The RC32332 integrates the RISCore 32300, the same CPU core found in the award-winning RC32364 microprocessor. The RISCore 32300 implements the Enhanced MIPS-II ISA. Thus, it is upwardly compatible with applications written for a wide variety of MIPS architecture processors, and it is kernel compatible with the modern operating systems that support IDT's 64-bit RISController product family. The RISCore 32300 was explicitly defined and designed for integrated processor products such as the RC32332. Key attributes of the execution core found within this product include:

- ◆ High-speed, 5-stage scalar pipeline executes to 150MHz. This high performance enables the RC32332 to perform a variety of performance intensive tasks, such as routing, DSP algorithms, etc.
- ◆ 32-bit architecture with enhancements of key capabilities. Thus, the RC32332 can execute existing 32-bit programs, while enabling designers to take advantage of recent advances in CPU architecture.
- ◆ Count leading-zeroes/ones. These instructions are common to a wide variety of tasks, including modem emulation, voice over IP compression and decompression, etc.
- ◆ Cache PREFetch instruction support, including a specialized form intended to help memory coherency. System programmers can allocate and stage the use of memory bandwidth to achieve maximum performance.
- ◆ 8KB of 2-way set associative instruction cache

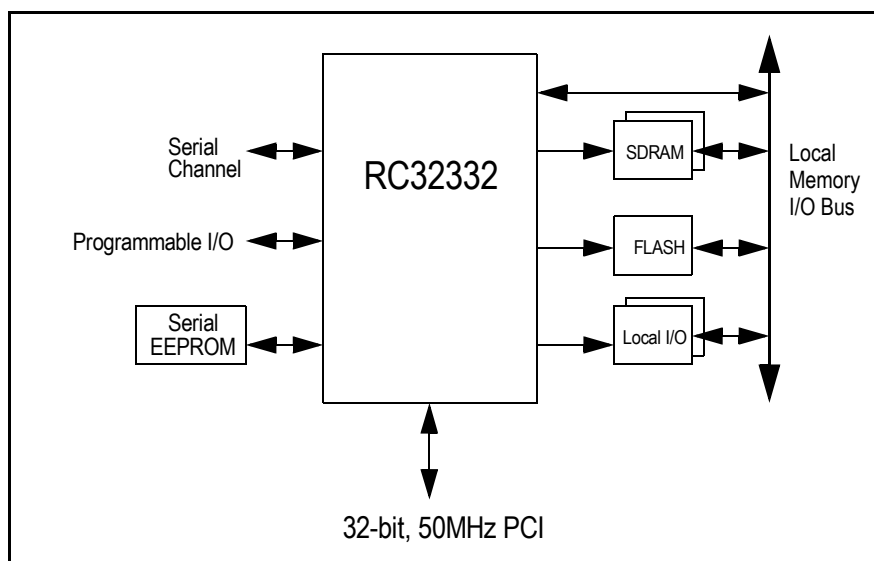


Figure 2 RC32332 Based System Diagram

- ◆ 2KB of 2-way set associative data cache, capable of write-back and write-through operation.
- ◆ Cache locking per line to speed real-time systems and critical system functions
- ◆ On-chip TLB to enable multi-tasking in modern operating systems
- ◆ EJTAG interface to enable sophisticated low-cost in-circuit emulation.

Synchronous-DRAM Interface

The RC32332 integrates a SDRAM controller which provides direct control of system SyncDRAM running at speeds to 75MHz.

Key capabilities of the SDRAM controller include:

- ◆ Direct control of 4 banks of SDRAM (up to 2 64-bit wide DIMMs)
- ◆ On-chip page comparators optimize access latency.
- ◆ Speeds to 75MHz
- ◆ Programmable address map.
- ◆ Supports 16, 64, 128, 256, or 512Mb SDRAM devices
- ◆ Automatic refresh generation driven by on-chip timer
- ◆ Support for discrete devices, SODIMM, or DIMM modules.

Thus, systems can take advantage of the full range of commodity memory that is available, enabling system optimization for cost, real-estate, or other attributes.

Local Memory and I/O Controller

The local memory and I/O controller implements direct control of external memory devices, including the boot ROM as well as other memory areas, and also implements direct control of external peripherals.

The local memory controller is highly flexible, allowing a wide range of devices to be directly controlled by the RC32332 processor. For example, a system can be built using an 8-bit boot ROM, 16-bit FLASH cards (possibly on PCMCIA), a 32-bit SRAM or dual-port memory, and a variety of low-cost peripherals.

Key capabilities include:

- ◆ Direct control of EPROM, FLASH, RAM, and dual-port memories
- ◆ 6 chip-select outputs, supporting up to 8MB per memory space
- ◆ Supports mixture of 8-, 16-, and 32-bit wide memory regions
- ◆ Flexible timing protocols allow direct control of a wide variety of devices
- ◆ Programmable address map for 2 chip selects
- ◆ Automatic wait state generation.

PCI Bus Bridge

In order to leverage the wide availability of low-cost peripherals for the PC market as well as to simplify the design of add-in functions, the RC32332 integrates a full 32-bit PCI bus bridge. Key attributes of this bridge include:

- ◆ 50 MHz operation
- ◆ PCI revision 2.2 compliant
- ◆ Programmable address mappings between CPU/Local memory and PCI memory and I/O
- ◆ On-chip PCI arbiter
- ◆ Extensive buffering allows PCI to operate concurrently with local memory transfers
- ◆ Selectable byte-ordering swapper.

On-Chip DMA Controller

To minimize CPU exception handling and maximize the efficiency of system bandwidth, the RC32332 integrates a very sophisticated 4-channel DMA controller on chip.

The RC32332 DMA controller is capable of:

- ◆ Chaining and scatter/gather support through the use of a flexible, linked list of DMA transaction descriptors
- ◆ Capable of memory<->memory, memory<->I/O, and PCI<->memory DMA
- ◆ Unaligned transfer support
- ◆ Byte, halfword, word, quadword DMA support.

On-Chip Peripherals

The RC32332 also integrates peripherals that are common to a wide variety of embedded systems.

- ◆ Single 16550 compatible UART.
- ◆ SPI master mode interface for direct interface to EEPROM, A/D, etc.
- ◆ Interrupt Controller to speed interrupt decode and management
- ◆ Four 32-bit on-chip Timer/Counters
- ◆ Programmable I/O module

Debug Support

To facilitate rapid time to market, the RC32332 provides extensive support for system debug.

First and foremost, this product integrates an EJTAG in-circuit emulation module, allowing a low-cost emulator to interoperate with programs executing on the controller. By using an augmented JTAG interface, the RC32332 is able to reuse the same low-cost emulators developed around the RC32364 CPU.

Secondly, the RC32332 implements additional reporting signals intended to simplify the task of system debugging when using a logic analyzer. This product allows the logic analyzer to differentiate transactions initiated by DMA from those initiated by the CPU and further allows CPU transactions to be sorted into instruction fetches vs. data fetches.

Finally, the RC32332 implements a full boundary scan capability, allowing board manufacturing diagnostics and debug.

Packaging

The RC32332 is packaged using a 208 Quad Flat Pack (QFP) package.

Thermal Considerations

The RC32332 consumes less than 2.0 W peak power. The device is guaranteed in an ambient temperature range of 0° to +70° C for commercial temperature devices; -40° to +85° C for industrial temperature devices.

Revision History

November 15, 2000: Initial publication.

December 12, 2000: Changed Max values for `cpu_masterclock` period in Table 5 and added footnote. In Table 1, added 2nd alternate function for `spi_mosi`, `spi_miso`, `spi_sck`. In Table 11, added "2" in Alt column for pins 186, 187, 188. In RC32332 Alternate Signal Functions table, added pin names in Alt #2 column for pins 186, 187, 188.

January 4, 2001: In Table 6 under Interrupt Handling, changed `Tdoh9` to `Thld13` and moved the values for `Tsu9` from the Max to the Min column.

February 23, 2001: In Table 1, changed alternate function for `uart_tx[0]` from `PIO[3]` to `PIO[1]`. In Table 11, changed the number of alternate pins for Pin 156 from 1 to 2. In Table 12, added `PIO[7]` to Alt #2 column for Pin 156 and changed `PIO[3]` to `PIO[1]` for Pin 207.

March 13, 2001: Changed upper ambient temperature for industrial and commercial uses from +70° C to +85° C.

June 7, 2001: In the Clock Parameters table, added footnote 3 to `output_clk` category and added NA to Min and Max columns. In Figure 3 (Reset Specification), enhanced signal line for `cpu_masterclk`. In Local System Interface section of AC Timing Characteristics table, changed values in Min column for last category of signals (`Tdoh3`) from 1.5 to 2.5 for both speeds. In SDRAM Controller section of same table, changed values in Min column for last category of signals (9 signals) from 1 to 2.5 for both speeds.

September 14, 2001: In the Reset category of Table 6: switched `mem_addr[19:17]` from `Tsu22` and `Thld22` to `Tsu10` and `Thld10`; switched `mem_addr[22:20]` from `Tsu10` and `Thld10` to `Tsu22` and `Thld22`; moved `ejtag_pcst[2:0]` from Reset to Debug Interface category under `Tsu20` and `Thld20`.

November 1, 2001: Added Input Voltage Undershoot parameter and 2 footnotes to Table 10. Changed to DH package.

May 2, 2002: Changed from PCI 2.1 to 2.2 compliant. Added 512 MB SDRAM support. Changed upper ambient temperature for commercial uses back from +85° C to +70° C (changed erroneously from 70 to 85 on March 13, 2001). Added Reset State Status column to Table 1. Revised description of `jtag_trst_n` in Table 1 and changed this pin to a pull-down instead of a pull-up.

July 3, 2002: This data sheet now describes revision Y silicon and is no longer applicable to revision Z.

July 12, 2002: Added 150MHz speed grade. In Table 6: DMA section, changed `Thld9` Min values from 2 to 1; in PIO section, changed `Thld9` Min values from 2 to 1. Changed revision Y data sheet from Preliminary to Final.

September 18, 2002: Added `cpu_coldreset_n` rise time to Table 5, Clock Parameters. Added `mem_addr[16]` and `sdram_addr[16]` to Tables 1 and 12. Changed Logic Diagram to include `sdram_addr[16]`.

December 18, 2002: In the Reset section of Table 6, AC Timing Characteristics, setup and hold time categories for `cpu_coldreset_n` have been deleted.

September 2, 2003: Added 2.5V version of device. Changed tables to include 2.5V values where appropriate. Added a Power Consumption table, Temperature and Voltage table, and Power Curves for the 2.5V device. In the PCI category of Table 6, created separate sections for 3.3V and 2.5V devices and in 2.5V section changed time to 4 ns for `pci_cbe_n[3:0]`, `pci_frame_n`, `pci_trdy_n`, and `pci_irdy_n`. In Table 8, added 3 new categories (Input Pads, PCI Input Pads, and All Pads) and added footnotes 2 and 3. In Table 13, pins 181 and 184 were changed from Vcc Core to Vcc I/O.

March 24, 2004: In Table 1, changed description in Satellite Mode for `pci_rst_n`. Specified "cold" reset on pages 12 and 13. Changed several values in Table 12, Absolute Maximum Ratings, and changed footnote 1 to that table.

May 4, 2004: Revised values in Table 9, Power Consumption.

Pin Description Table

The following table lists the pins provided on the RC32332. Note that those pin names followed by “_n” are active-low signals. All external pull-ups and pull-downs require 10 kΩ resistor.

Name	Type	Reset State Status	Drive Strength Capability	Description																														
Local System Interface																																		
mem_data[31:0]	I/O	Z	High	Local system data bus Primary data bus for memory. I/O and SDRAM.																														
mem_addr[22:2]	I/O	[22:10] Z [9:2] L	[22:17] Low [16:2] High	Memory Address Bus These signals provide the Memory or DRAM address, during a Memory or DRAM bus transaction. During each word data, the address increments either in linear or sub-block ordering, depending on the transaction type. The table below indicates how the memory write enable signals are used to address discreet memory port width types. <table border="1"> <thead> <tr> <th>Port Width</th><th colspan="4">Pin Signals</th></tr> <tr> <th></th><th>mem_we_n[3]</th><th>mem_we_n[2]</th><th>mem_we_n[1]</th><th>mem_we_n[0]</th></tr> </thead> <tbody> <tr> <td>DMA (32-bit)</td><td>mem_we_n[3]</td><td>mem_we_n[2]</td><td>mem_we_n[1]</td><td>mem_we_n[0]</td></tr> <tr> <td>32-bit</td><td>mem_we_n[3]</td><td>mem_we_n[2]</td><td>mem_we_n[1]</td><td>mem_we_n[0]</td></tr> <tr> <td>16-bit</td><td>Byte High Write Enable</td><td>mem_addr[1]</td><td>Not Used (Driven Low)</td><td>Byte Low Write Enable</td></tr> <tr> <td>8-bit</td><td>Not Used (Driven High)</td><td>mem_addr[1]</td><td>mem_addr[0]</td><td>Byte Write Enable</td></tr> </tbody> </table> mem_addr[22] Alternate function: reset_boot_mode[1]. mem_addr[21] Alternate function: reset_boot_mode[0]. mem_addr[20] Alternate function: reset_pci_host_mode. mem_addr[19] Alternate function: modebit [9]. mem_addr[18] Alternate function: modebit [8]. mem_addr[17] Alternate function: modebit [7]. mem_addr[16] Alternate function: sdram_addr[16]. mem_addr[15] Alternate function: sdram_addr[15]. mem_addr[14] Alternate function: sdram_addr[14]. mem_addr[13] Alternate function: sdram_addr[13]. mem_addr[11] Alternate function: sdram_addr[11]. mem_addr[10] Alternate function: sdram_addr[10]. mem_addr[9] Alternate function: sdram_addr[9]. mem_addr[8] Alternate function: sdram_addr[8]. mem_addr[7] Alternate function: sdram_addr[7]. mem_addr[6] Alternate function: sdram_addr[6]. mem_addr[5] Alternate function: sdram_addr[5]. mem_addr[4] Alternate function: sdram_addr[4]. mem_addr[3] Alternate function: sdram_addr[3]. mem_addr[2] Alternate function: sdram_addr[2].	Port Width	Pin Signals					mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable	8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable
Port Width	Pin Signals																																	
	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																														
DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																														
32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																														
16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable																														
8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable																														
mem_cs_n[5:0]	Output	H	Low	Memory Chip Select Negated Recommend an external pull-up. Signals that a Memory Bank is actively selected.																														
mem_oe_n	Output	H	High	Memory Output Enable Negated Recommend an external pull-up. Signals that a Memory Bank can output its data lines onto the cpu_ad bus.																														
mem_we_n[3:0]	Output	H	High	Memory Write Enable Negated Bus Signals which bytes are to be written during a memory transaction. Bits act as Byte Enable and mem_addr[1:0] signals for 8-bit or 16-bit wide addressing.																														

Table 1 Pin Descriptions (Part 1 of 6)

Name	Type	Reset State Status	Drive Strength Capability	Description
mem_wait_n	Input		—	Memory Wait Negated Requires an external pull-up. SRAM/IOI/IOM modes: Allows external wait-states to be injected during the last cycle before data is sampled. DPM (dual-port) mode: Allows dual-port busy signal to restart memory transaction. Alternate function: sdram_wait_n.
mem_245_oe_n	Output	H	Low	Memory FCT245 Output Enable Negated Controls output enable to optional FCT245 transceiver bank by asserting during both reads and writes to a memory or I/O bank.
mem_245_dt_r_n	Output	Z	High	Memory FCT245 Direction Xmit/Rcv Negated Recommend an external pull-up. Alternate function: cpu_dt_r_n. See CPU Core Specific Signals below.
output_clk	Output	cpu_masterclk	High	Output Clock Optional clock output.

PCI Interface

pci_ad[31:0]	I/O	Z	PCI	PCI Multiplexed Address/Data Bus Address driven by Bus Master during initial frame_n assertion, and then the Data is driven by the Bus Master during writes; or the Data is driven by the Bus Slave during reads.
pci_cbe_n[3:0]	I/O	Z	PCI	PCI Multiplexed Command/Byte Enable Bus Command (not negated) Bus driven by the Bus Master during the initial frame_n assertion. Byte Enable Negated Bus driven by the Bus Master during the data phase(s).
pci_par	I/O	Z	PCI	PCI Parity Even parity of the pci_ad[31:0] bus. Driven by Bus Master during Address and Write Data phases. Driven by the Bus Slave during the Read Data phase.
pci_frame_n	I/O	Z	PCI	PCI Frame Negated Driven by the Bus Master. Assertion indicates the beginning of a bus transaction. De-assertion indicates the last datum.
pci_trdy_n	I/O	Z	PCI	PCI Target Ready Negated Driven by the Bus Slave to indicate the current datum can complete.
pci_irdy_n	I/O	Z	PCI	PCI Initiator Ready Negated Driven by the Bus Master to indicate that the current datum can complete.
pci_stop_n	I/O	Z	PCI	PCI Stop Negated Driven by the Bus Slave to terminate the current bus transaction.
pci_idsel_n	Input		—	PCI Initialization Device Select Uses pci_req_n[2] pin. See the PCI subsection.
pci_perr_n	I/O	Z	PCI	PCI Parity Error Negated Driven by the receiving Bus Agent 2 clocks after the data is received, if a parity error occurs.
pci_serr_n	I/O Open-collector	Z	PCI	System Error Requires an external pull-up. Driven by any agent to indicate an address parity error, data parity during a Special Cycle command, or any other system error.
pci_clk	Input		—	PCI Clock Clock for PCI Bus transactions. Uses the rising edge for all timing references.
pci_rst_n	Input	L	—	PCI Reset Negated Host mode: Resets all PCI related logic. Satellite mode: Resets all PCI related logic and also warm resets the 32332.
pci_devsel_n	I/O	Z	PCI	PCI Device Select Negated Driven by the target to indicate that the target has decoded the present address as a target address.

Table 1 Pin Descriptions (Part 2 of 6)

Name	Type	Reset State Status	Drive Strength Capability	Description
pci_req_n[2]	Input	Z	—	PCI Bus Request #2 Negated Requires an external pull-up. Host mode: pci_req_n[2] is an input indicating a request from an external device. Satellite mode: used as pci_idsel pin which selects this device during a configuration read or write. Alternate function: pci_idsel (satellite).
pci_req_n[0]	I/O	Z	High	PCI Bus Request #0 Negated Requires an external pull-up for burst mode. Host mode: pci_req_n[0] is an input indicating a request from an external device. Satellite mode: pci_req_n[0] is an output indicating a request from this device.
pci_gnt_n[2]	Output	Z ¹	High	PCI Bus Grant #2 Negated Recommend an external pull-up. Host mode: pci_gnt_n[2] is an output indicating a grant to an external device. Satellite mode: pci_gnt_n[2] is used as the pci_inta_n output pin. External pull-up is required. Alternate function: pci_inta_n (satellite).
pci_gnt_n[1] (can only be used as alternate function)	I/O	X for 1 pci clock then H ²	High	PCI Bus Grant #1 Negated Recommend external pull-up. Host mode: not used as pci_gnt_n[1]. Must be used as alternate function PIO[7]. Satellite mode: Not used as pci_gnt_n[1]. Used as pci_eprom_cs output pin for Serial Chip Select for loading PCI Configuration Registers in the RC32332 Reset Initialization Vector PCI boot mode. Defaults to the output direction at reset time. 1st Alternate function: pci_eeprom_cs (satellite). 2nd Alternate function: PIO[7].
pci_gnt_n[0]	I/O	Z	High	PCI Bus Grant #0 Negated Host mode: pci_gnt_n[0] is an output indicating a grant to an external device. Recommend external pull-up. Satellite mode: pci_gnt_n[0] is an input indicating a grant to this device. Requires external pull-up.
pci_inta_n	Output Open-collector	Z	PCI	PCI Interrupt #A Negated Uses pci_gnt_n[2]. See the PCI subsection.
pci_lock_n	Input		—	PCI Lock Negated Driven by the Bus Master to indicate that an exclusive operation is occurring.

¹ Z in host mode; L in satellite non-boot mode; Z in satellite boot mode.
² H in host mode, L in satellite non-boot and boot modes. X = unknown.

SDRAM Control Interface

sdram_addr_12	Output	L	High	SDRAM Address Bit 12 and Precharge All SDRAM mode: Provides SDRAM address bit 12 (10 on the SDRAM chip) during row address and "pre-charge all" signal during refresh, read and write command.
sdram_ras_n	Output	H	High	SDRAM RAS Negated SDRAM mode: Provides SDRAM RAS control signal to all SDRAM banks.
sdram_cas_n	Output	H	High	SDRAM CAS Negated SDRAM mode: Provides SDRAM CAS control signal to all SDRAM banks.
sdram_we_n	Output	H	High	SDRAM WE Negated SDRAM mode: Provides SDRAM WE control signal to all SDRAM banks.
sdram_cke	Output	H	High	SDRAM Clock Enable SDRAM mode: Provides clock enable to all SDRAM banks.
sdram_cs_n[3:0]	Output	H	High	SDRAM Chip Select Negated Bus Recommend an external pull-up. SDRAM mode: Provides chip select to each SDRAM bank. SODIMM mode: Provides upper select byte enables [7:4].
sdram_s_n[1:0]	Output	H	High	SDRAM SODIMM Select Negated Bus SDRAM mode: Not used. SDRAM SODIMM mode: Upper and lower chip selects.

Table 1 Pin Descriptions (Part 3 of 6)

Name	Type	Reset State Status	Drive Strength Capability	Description
sdram_bemask_n [3:0]	Output	H	High	SDRAM Byte Enable Mask Negated Bus (DQM) SDRAM mode: Provides byte enables for each byte lane of all DRAM banks. SODIMM mode: Provides lower select byte enables [3:0].
sdram_245_oe_n	Output	H	Low	SDRAM FCT245 Output Enable Negated Recommend an external pull-up. SDRAM mode: Controls output enable to optional FCT245 transceiver bank by asserting during both reads and writes to any DRAM bank.
sdram_245_dt_r_n	Output	Z	High	SDRAM FCT245 Direction Transmit/Receive Recommend an external pull-up. Uses cpu_dt_r_n. See CPU Core Specific Signals below.

On-Chip Peripherals

dma_ready_n[0]	I/O	Z	Low	DMA Ready Negated Bus Requires an external pull-up. Ready mode: Input pin for general purpose DMA channel 0 that can initiate the next datum in the current DMA descriptor frame. Done mode: Input pin for general purpose DMA channel 0 that can terminate the current DMA descriptor frame. dma_ready_n[0] 1st Alternate function PIO[0]; 2nd Alternate function: dma_done_n[0].
pio[7:0]	I/O	See related pins	Low	Programmable Input/Output General purpose pins that can each can be configured as a general purpose input or general purpose output. These pins are multiplexed with other pin functions: pci_gnt_n[1] (pci_eeprom_cs), spi_mosi, spi_sck, spi_ss_n, spi_miso, uart_rx[0], uart_tx[0], dma_ready_n[0]. Note that pci_gnt_n[1], spi_mosi, spi_sck, and spi_ss_n default to outputs at reset time. The others default to inputs.
uart_rx[0]	I/O	Z	Low	UART Receive Data Bus UART mode: UART channel receive data. uart_rx[0] Alternate function: PIO[2].
uart_tx[0]	I/O	Z	Low	UART Transmit Data Bus Recommend an external pull-up. UART mode: UART channel send data. Note that this pin defaults to an input at reset time and must be programmed via the PIO interface before being used as a UART output. uart_tx[0] Alternate function: PIO[1].
spi_mosi	I/O	L	Low	SPI Data Output Serial mode: Output pin from RC32332 as an Input to a Serial Chip for the Serial data input stream. In PCI satellite mode, acts as an Output pin from RC32332 that connects as an Input to a Serial Chip for the Serial data input stream for loading PCI Configuration Registers in the RC32332 Reset Initialization Vector PCI boot mode. 1st Alternate function: PIO[6]. Defaults to the output direction at reset time. 2nd Alternate function: pci_eeprom_mdo.
spi_miso	I/O	Z	Low	SPI Data Input Serial mode: Input pin to RC32332 from the Output of a Serial Chip for the Serial data output stream. In PCI satellite mode, acts as an Input pin from RC32332 that connects as an output to a Serial Chip for the Serial data output stream for loading PCI Configuration Registers in the RC32332 Reset Initialization Vector PCI boot mode. Defaults to input direction at reset time. 1st Alternate function: PIO[3]. 2nd Alternate function: pci_eeprom_mdi.
spi_sck	I/O	L	Low	SPI Clock Serial mode: Output pin for Serial Clock. In PCI satellite mode, acts as an Output pin for Serial Clock for loading PCI Configuration Registers in the RC32332 Reset Initialization Vector PCI boot mode. 1st Alternate function: PIO[5]. Defaults to the output direction at reset time. 2nd Alternate function: pci_eeprom_sk.

Table 1 Pin Descriptions (Part 4 of 6)

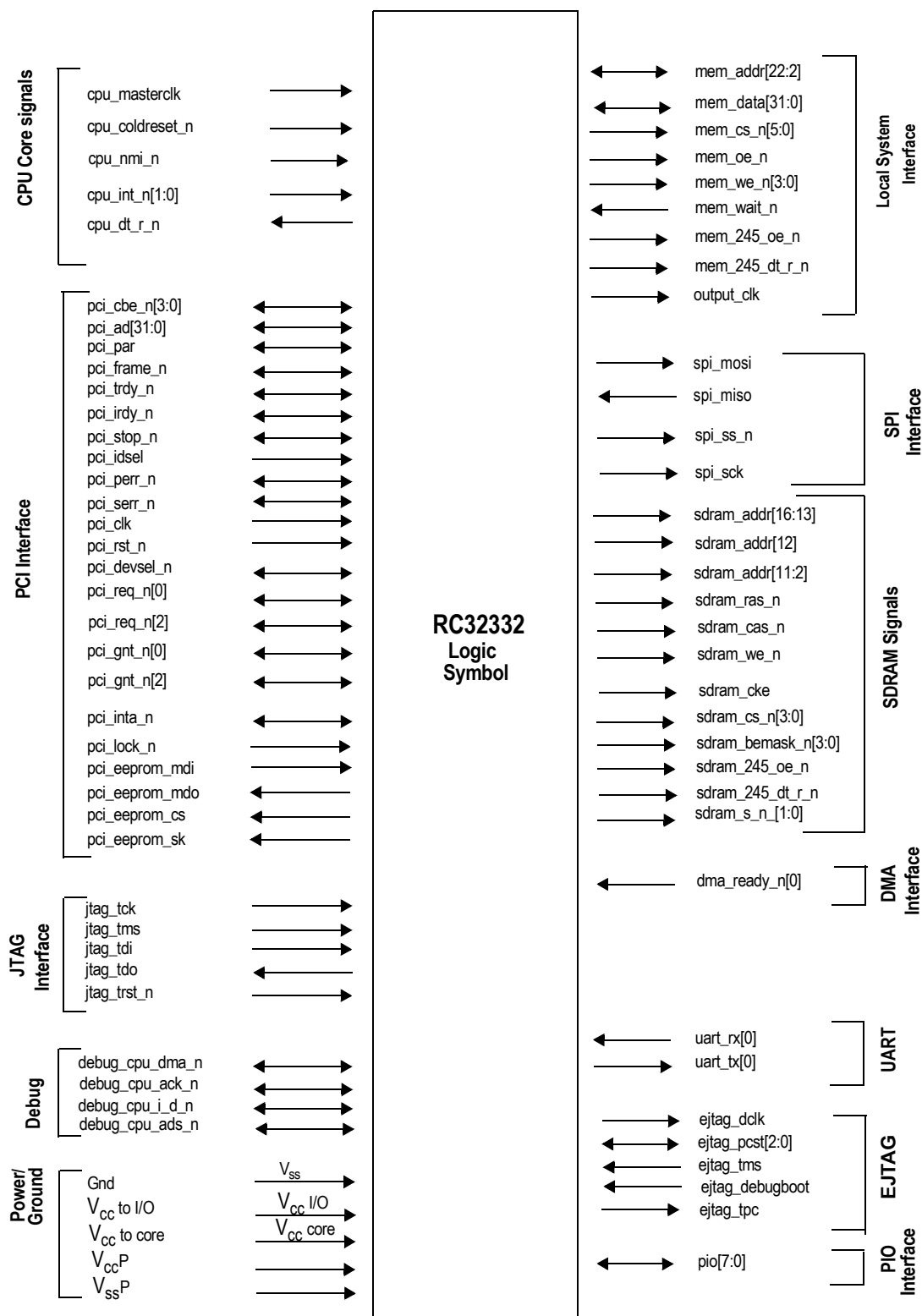
Name	Type	Reset State Status	Drive Strength Capability	Description
ejtag_pcst[2:0]	I/O	Z	Low	EJTAG PC Trace Status Information 111 (STL) Pipe line Stall 110 (JMP) Branch/Jump forms with PC output 101 (BRT) Branch/Jump forms with no PC output 100 (EXP) Exception generated with an exception vector code output 011 (SEQ) Sequential performance 010 (TST) Trace is outputted at pipeline stall time 001 (TSQ) Trace trigger output at performance time 000 (DBM) Run Debug Mode Alternate function: modebit[2:0].
ejtag_debugboot	Input		—	EJTAG DebugBoot Requires an external pull-down. The ejtag_debugboot input is used during reset and forces the CPU core to take a debug exception at the end of the reset sequence instead of a reset exception. This enables the CPU to boot from the ICE probe without having the external memory working. This input signal is level sensitive and is not latched internally. This signal will also set the JtagBrk bit in the JTAG_Control_Register[12].
ejtag_tms	Input		—	EJTAG Test Mode Select Requires an external pull-up. The ejtag_tms is sampled on the rising edge of jtag_tck.

Debug Signals

debug_cpu_dma_n	I/O	Z	Low	Debug CPU versus DMA Negated De-assertion high during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from the CPU. Assertion low during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from DMA. Alternate function: modebit[6].
debug_cpu_ack_n	I/O	Z	Low	Debug CPU Acknowledge Negated Indicates either a data acknowledge to the CPU or DMA. Alternate function: modebit[4].
debug_cpu_ads_n	I/O	Z	Low	Debug CPU Address/Data Strobe Negated Assertion indicates that either a CPU or a DMA transaction is beginning and that the mem_data[31:4] bus has the current block address. Alternate function: modebit[5].
debug_cpu_i_d_n	I/O	Z	Low	Debug CPU Instruction versus Data Negated Assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU or DMA data transaction. De-assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU instruction transaction. Alternate function: modebit[3].

Table 1 Pin Descriptions (Part 6 of 6)

Logic Diagram — RC32332



Mode Bit Settings to Configure Controller on Reset

The following table lists the mode bit settings to configure the controller on cold reset.

Pin	Mode Bit	Description	Value	Mode Setting
ejtag_pcst[2:0]	2:0 MSB (2)	Clock Multiplier MasterClock is multiplied internally to generate PClock	0	Multiply by 2
			1	Multiply by 3
			2	Multiply by 4
			3	Reserved
			4	Reserved
			5	Reserved
			6	Reserved
			7	Reserved
debug_cpu_i_d_n	3	EndBit	0	Little-endian ordering
			1	Big-endian ordering
debug_cpu_ack_n	4	Reserved	0	
debug_cpu_ads_n	5	Reserved	0	
debug_cpu_dma_n	6	TmrIntEn Enables/Disables the timer interrupt on Int*[5]	0	Enables timer interrupt
			1	Disables timer interrupt
mem_addr[17]	7	Reserved for future use	1	
mem_addr[19:18]	9:8 MSB (9)	Boot-Prom Width specifies the memory port width of the memory space which contains the boot prom.	00	8 bits
			01	16 bits
			10	32 bits
			11	Reserved

Table 2 Boot-Mode Configuration Settings

reset_boot_mode Settings

By using the non-boot mode cold reset initialization mode the user can change the internal register addresses from base 1800_0000 to base 1900_0000, as required. The RC32332 cold reset-boot mode initialization setting values and mode descriptions are listed below.

Pin	Reset Boot Mode	Description	Value	Mode Settings
mem_addr[22:21]	1:0 MSB (1)	Tri-state memory bus and EEPROM bus during coldreset_n assertion	11	Tri-state_bus_mode
		Reserved	10	
		PCI-boot mode (pci_host_mode must be in satellite mode) RC32332 will reset either from a cold reset or from a PCI reset. Boot code is provided via PCI.	01	PCI_boot_mode
		Standard-boot mode Boot from the RC32332's memory controller (typical system).	00	standard_boot_mode

Table 3 RC32332 reset_boot_mode Initialization Settings

AC Timing Characteristics — RC32332

Ta Commercial = 0°C to +70°C; Ta Industrial = -40°C to +85°C

3.3V version: V_{cc} Core = +3.3V±5%; V_{cc} I/O = +3.3V±5%2.5V version: V_{cc} Core = +2.5V±5%; V_{cc} I/O = +3.3V±5%

Signal	Symbol	Reference Edge	100MHz ¹		133MHz ¹		150MHz ¹		Units	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		
Local System Interface										
mem_data[31:0] (data phase)	Tsu2	cpu_masterclk rising	6	—	5	—	4.8	—	ns	Chapter 9, Figures 9.2 and 9.3
mem_data[31:0] (data phase)	Thld2	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	
cpu_dt_r_n	Tdo3	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_data[31:0]	Tdo4	cpu_masterclk rising	—	12	—	10	—	9.3	ns	Chapter 10, Figures 10.6 through 10.8
mem_data[31:0] output hold time	Tdoh1	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_data[31:0] (tristate disable time)	Tdz	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_data[31:0] (tristate to data time)	Tzd	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_wait_n	Tsu6	cpu_masterclk rising	9	—	7	—	6	—	ns	
mem_wait_n	Thld8	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_addr[22:2]	Tdo5	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_cs_n[5:0]	Tdo6	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_oe_n, mem_245_oe_n	Tdo7	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_we_n[3:0]	Tdo7a	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_245_dt_r_n	Tdo8	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_addr[25:2] mem_cs_n[5:0] mem_oe_n, mem_we_n[3:0], mem_245_dt_r_n, mem_245_oe_n	Tdoh3	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	
PCI for 3.3V Device ³										
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n	Tsu	pci_clk rising	3	—	3	—	3	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_gnt_n[0]	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Thld	pci_clk rising	0	—	0	—	0	—	ns	

Table 6 AC Timing Characteristics - RC32332 (Part 1 of 4)

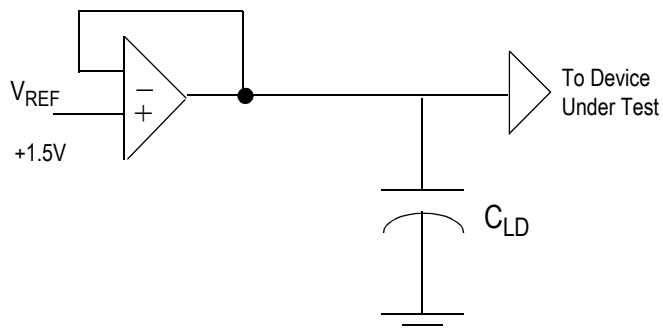
Signal	Symbol	Reference Edge	100MHz ¹		133MHz ¹		150MHz ¹		Units	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_eeprom_mdi	Tsu	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdi	Thld	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdo, pci-eepprom_cs	Tdo	pci_clk rising, pci_eeprom_sk falling	—	15	—	12	—	10	ns	
pci_eeprom_sk	Tdo	pci_clk rising	—	15	—	12	—	10	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n	Tdo	pci_clk rising	2	7.5	2	7.5	2	7.5	ns	
pci_req_n[0], pci_gnt_n[2], pci_gnt_n[1], pci_gnt_n[0], pci_inta_n	Tdo	pci_clk rising	2	7.5	2	7.5	2	7.5	ns	

PCI for 2.5V Device³

pci_ad[31:0], pci_par, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Tsu	pci_clk rising	3	—	3	—	3	—	ns	
pci_cbe_n[3:0], pci_frame_n, pci_trdy_n, pci_irdy_n	Tsu	pci_clk rising	4	—	4	—	4	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_gnt_n[0]	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ⁴	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_eeprom_mdi	Tsu	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdi	Thld	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	
pci_eeprom_mdo, pci-eepprom_cs	Tdo	pci_clk rising, pci_eeprom_sk falling	—	15	—	12	—	10	ns	
pci_eeprom_sk	Tdo	pci_clk rising	—	15	—	12	—	10	ns	

Table 6 AC Timing Characteristics - RC32332 (Part 2 of 4)

Output Loading for AC Testing



Signal	C _{ld}
All High Drive Signals	50 pF
All Low Drive Signals	25 pF

Figure 5 Output Loading for AC Testing

Note: PCI pins have been correlated to PCI 2.2.

Recommended Operation Temperature and Supply Voltage

3.3V Device

Grade	Ambient Temperature	Gnd	V _{ccIO}	V _{ccCore}	V _{ccP}
Commercial	0°C to +70°C Ambient	0V	3.3V±5%	3.3V±5%	3.3V±5%
Industrial	-40°C to +85°C Ambient	0V	3.3V±5%	3.3V±5%	3.3V±5%

Table 7 Temperature and Voltage — 3.3V Device

2.5V Device

Grade	Ambient Temperature	Gnd	V _{ccIO}	V _{ccCore}	V _{ccP}
Commercial	0°C to +70°C Ambient	0V	3.3V±5%	2.5V±5%	2.5V±5%
Industrial	-40°C to +85°C Ambient	0V	3.3V±5%	2.5V±5%	2.5V±5%

Table 8 Temperature and Voltage — 2.5V Device

DC Electrical Characteristics — RC32332

Ta Commercial = 0°C to +70°C; Ta Industrial = -40°C to +85°C

3.3V version: V_{CC} Core = +3.3V±5%; V_{CC} I/O = +3.3V±5%

2.5V version: V_{CC} Core = +2.5V±5%; V_{CC} I/O = +3.3V±5%

	Parameter	RC32332 ¹		Pin Numbers	Conditions
		Minimum	Maximum		
Input Pads	V_{IL}	—	0.8V	52, 64, 95, 160, 161, 164, 166-169, 176, 191	—
	V_{IH}	2.0V	—		—
LOW Drive Output Pads	V_{OL}	—	0.4V	41-45, 48, 170, 171, 174, 175, 177-180, 185-190, 195-200, 207, 208	$ I_{OUT} = 6mA$
	V_{OH}	$V_{CC} - 0.4V$	—		$ I_{OUT} = 8mA$
	V_{IL}	—	0.8V		—
	V_{IH}	2.0V	—		—
HIGH Drive Output Pads	V_{OL}	—	0.4V	1- 5, 8, 13-15, 18-25, 28-35, 38-40, 49-51, 53- 57, 60, 61, 63, 65-67, 70-76, 79, 80, 83-87, 90-94, 153, 154, 156, 158, 165, 194, 201, 204, 205, 206	$ I_{OUT} = 7mA$
	V_{OH}	$V_{CC} - 0.4V$	—		$ I_{OUT} = 16mA$
	V_{IL}	—	0.8V		—
	V_{IH}	2.0V	—		—
PCI Drive Input Pads	V_{IL}	—	—	123, 155, 157, 159	Per PCI 2.2
	V_{IH}	—	—		
PCI Drive Output Pads	V_{OL}	—	—	96, 97, 100-109, 112-119, 122, 124-129, 132-139, 142-149, 152	Per PCI 2.2
	V_{OH}	—	—		
	V_{IL}	—	—		
	V_{IH}	—	—		
All Pads	C_{IN}	—	10pF	All input pads except 155 and 156	—
	C_{IN}^2	5pf	12pF	155	Per PCI 2.2
	C_{IN}^3	—	8pF	156	Per PCI 2.2
	C_{OUT}	—	10pF	All output pads	—
	I/O_{LEAK}	—	10μA	All non-internal pull-up pins	Input/Output Leakage
	I/O_{LEAK}	—	50μA	All internal pull-up pins	Input/Output Leakage

Table 9 DC Electrical Characteristics - RC32332

¹. At all pipeline frequencies.

². Applies only to pad 155.

³. Applies only to pad 156.

Capacitive Load Deration — RC32332

Refer to the IDT document [79RC32332 IBIS Model](#) located on the company's web site.

Power Curves

The following four graphs contain the simulated power curves that show power consumption at various bus frequencies. Figures 6 and 7 apply to the 3.3V device, while Figures 8 and 9 apply to the 2.5V device.

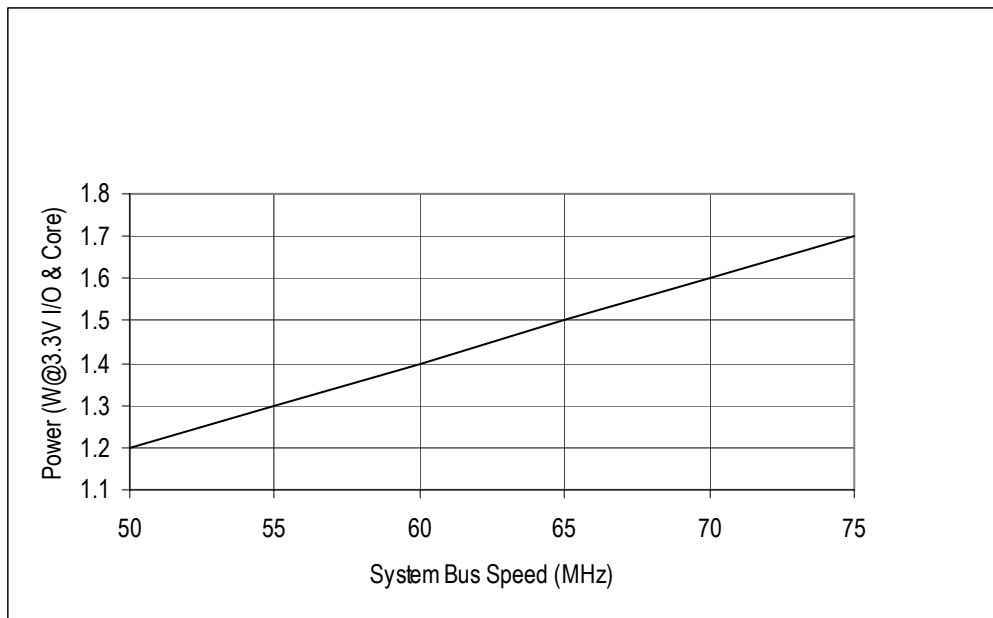


Figure 6 Typical Power Usage — RC32V332 Device

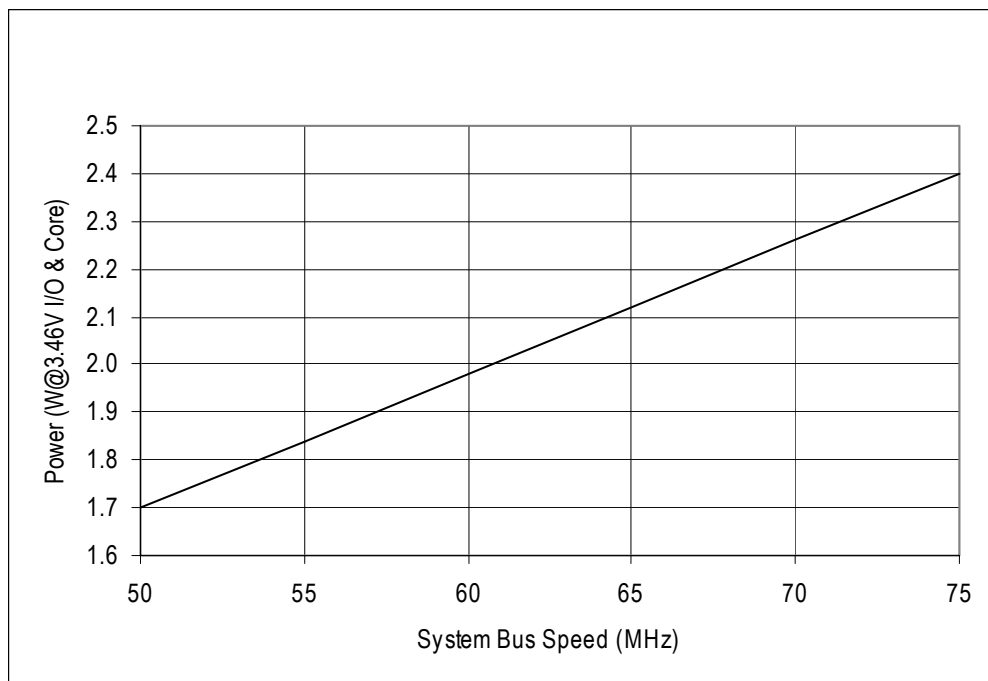


Figure 7 Maximum Power Usage — RC32V332 Device

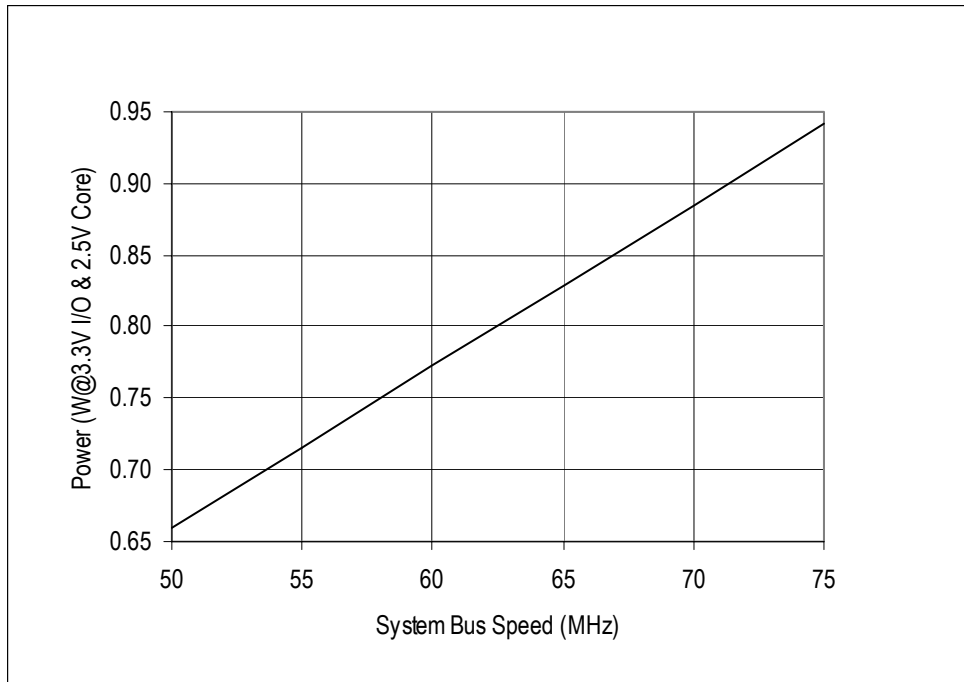


Figure 8 Typical Power Usage — RC32T332 Device

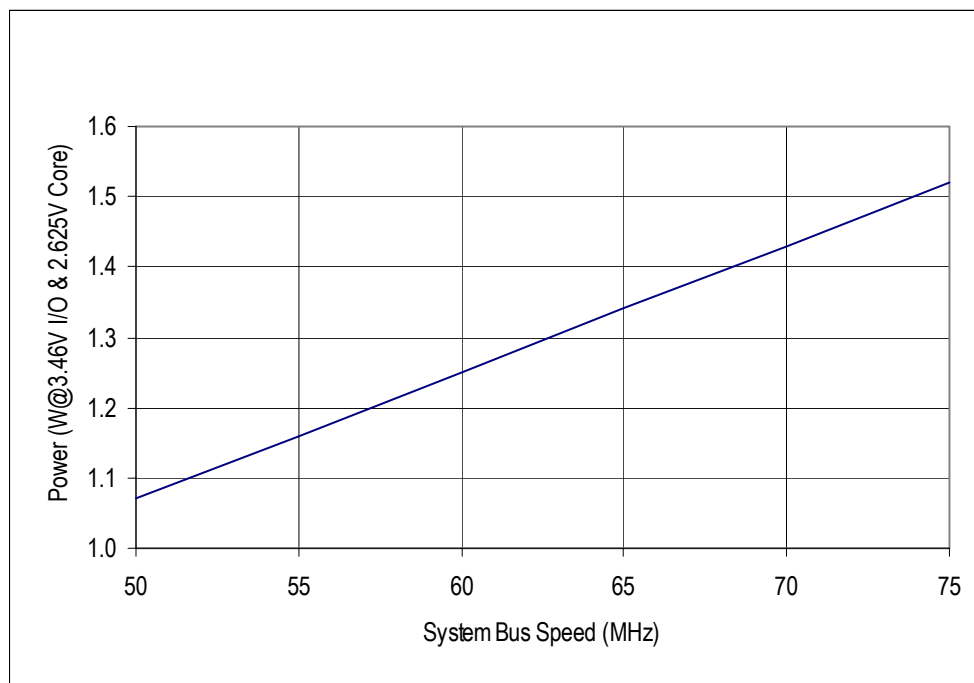


Figure 9 Maximum Power Usage — RC32T332 Device

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
20	mem_addr[7]	1	72	mem_data[2]		124	pci_stop_n		176	ejtag_debugboot	
21	mem_addr[8]	1	73	mem_data[28]		125	pci_devsel_n		177	debug_cpu_i_d_n	1
22	mem_addr[9]	1	74	mem_data[3]		126	pci_trdy_n		178	debug_cpu_ads_n	1
23	mem_addr[10]	1	75	mem_data[27]		127	pci_irdy_n		179	debug_cpu_ack_n	1
24	mem_addr[11]	1	76	mem_data[4]		128	pci_frame_n		180	debug_cpu_dma_n	1
25	output_clk		77	V _{cc} P		129	pci_cbe_n[2]		181	V _{cc} I/O	
26	V _{ss}		78	V _{ss} P		130	V _{ss}		182	V _{ss}	
27	V _{cc} core		79	mem_data[26]		131	V _{cc} core		183	V _{cc} core	
28	mem_addr_12		80	mem_data[5]		132	pci_ad[16]		184	V _{cc} I/O	
29	sdram_addr_12		81	V _{ss}		133	pci_ad[17]		185	spi_ss_n	1
30	sdram_cke		82	V _{cc} core		134	pci_ad[18]		186	spi_sck	2
31	sdram_cs_n[2]		83	cpu_dt_r_n	2	135	pci_ad[19]		187	spi_miso	2
32	sdram_cs_n[3]		84	mem_data[25]		136	pci_ad[20]		188	spi_mosi	2
33	sdram_bemask_n[2]		85	mem_data[6]		137	pci_ad[21]		189	dma_ready_n[0]	2
34	sdram_bemask_n[3]		86	mem_data[24]		138	pci_ad[22]		190	mem_245_oe_n	
35	mem_addr[13]		87	mem_data[7]		139	pci_ad[23]		191	mem_wait_n	2
36	V _{ss}		88	V _{ss}		140	V _{ss}		192	V _{ss}	
37	V _{cc} I/O		89	V _{cc} I/O		141	V _{cc} I/O		193	V _{cc} I/O	
38	mem_addr[14]		90	mem_data[23]		142	pci_cbe_n[3]		194	mem_oe_n	
39	mem_addr[15]	1	91	mem_data[8]		143	pci_ad[24]		195	mem_cs_n[0]	
40	mem_addr[16]	1	92	mem_data[22]		144	pci_ad[25]		196	mem_cs_n[1]	
41	mem_addr[17]	1	93	mem_data[9]		145	pci_ad[26]		197	mem_cs_n[2]	
42	mem_addr[18]	1	94	mem_data[21]		146	pci_ad[27]		198	mem_cs_n[3]	
43	mem_addr[19]	1	95	cpu_nmi_n		147	pci_ad[28]		199	mem_cs_n[4]	
44	mem_addr[20]	1	96	pci_ad[0]		148	pci_ad[29]		200	mem_cs_n[5]	
45	mem_addr[21]	1	97	pci_ad[1]		149	pci_ad[30]		201	mem_we_n[0]	
46	V _{ss}		98	V _{ss}		150	V _{ss}		202	V _{ss}	
47	V _{cc} I/O		99	V _{cc} I/O		151	V _{cc} I/O		203	V _{cc} I/O	
48	mem_addr[22]	1	100	pci_ad[2]		152	pci_ad[31]		204	mem_we_n[1]	
49	mem_data[10]		101	pci_ad[3]		153	pci_req_n[0]		205	mem_we_n[2]	
50	mem_data[11]		102	pci_ad[4]		154	pci_gnt_n[0]		206	mem_we_n[3]	
51	mem_data[20]		103	pci_ad[5]		155	pci_clk		207	uart_tx[0]	1
52	cpu_coldreset_n		104	pci_ad[6]		156	pci_gnt_n[1]	2	208	uart_rx[0]	1

Table 13 RC32332 208-pin QFP Package Pin-Out (Part 2 of 2)

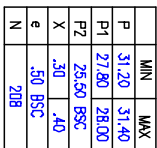
RC32332 Alternate Signal Functions

Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2
13	sdram_addr[2]		40	sdram_addr[16]		174	modebit[2]	
14	sdram_addr[3]		41	modebit[7]		177	modebit[3]	
15	sdram_addr[4]		42	modebit[8]		178	modebit[5]	
18	sdram_addr[5]		43	modebit[9]		179	modebit[4]	
19	sdram_addr[6]		44	reset_pci_host_mode		180	modebit[6]	
20	sdram_addr[7]		45	reset_boot_mode[0]		185	PIO[4]	
21	sdram_addr[8]		48	reset_boot_mode[1]		186	PIO[5]	pci_eeeprom_sk
22	sdram_addr[9]		83	mem_245_dt_r_n	sdram_245_dt_r_n	187	PIO[3]	pci_eeeprom_mdi
23	sdram_addr[10]		156	pci_eeeprom_cs (satellite)	PIO[7]	188	PIO[6]	pci_eeeprom_mdo
24	sdram_addr[11]		157	pci_idsel (satellite)		189	PIO[0]	dma_done_n[0]
35	sdram_addr[13]		158	pci_inta_n (satellite)		191	sdram_wait_n	mem_wait_n
38	sdram_addr[14]		170	modebit[0]		207	PIO[1]	
39	sdram_addr[15]		171	modebit[1]		208	PIO[2]	

Table 14 RC32332 Alternate Signal Functions

REV. VERSIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
28253	D0	INITIAL RELEASE	08/20/96	T. WU
61478	D1	ADD 'D' PACKAGE OPTION	09/20/98	T. WU
61829	D2	ADD 'D' PACKAGE OPTION	01/30/99	

LAND PATTERN DIMENSIONS



NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- 2 TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm
- 3 DATUMS [A-B] AND [D-D'] TO BE DETERMINED AT DATUM PLANE [H]
- 4 DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE [C-C']
- 5 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH
- 6 DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- 7 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIIUS OR THE FOOT.
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL
- 9 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-143, VARIATION FA-1

TOLSON/DAUGHERTY		DATE		TITLE	
SPECIAL AGENT		10/27/96		05/04/DR PACKAGE OUTLINE	
FBI		BY		26.0 X 26.0 X 3.4 mm PQPR	
10/27/96		1.30, 25 MIN FPM			
PSC-4059		REV			
SHEET 2 OF 2					

Ordering Information

79RCXX	V	DDD	SSS	PP	
Product Type	Operating Voltage	Device Type	CPU Frequency	Package	Temp range/ Process
					Blank = Commercial Temperature (0° C to +70° C Ambient)
					I = Industrial Temperature (-40° C to +85° C Ambient)
					DH = 208-pin PQFP
		332	100MHz 133MHz 150MHz		
	V = 3.3V ±5% T = 2.5V ±5%				

79RC32 = 32-bit family product

Valid Combinations

3.3V Device

79RC32V332 - 100DH, 133DH, 150DH	Commercial
79RC32V332 - 100DHI, 133DHI, 150DHI	Industrial

2.5V Device

79RC32T332 - 100DH, 133DH, 150DH	Commercial
79RC32T332 - 100DHI, 133DHI, 150DHI	Industrial



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